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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

This application is a DIV of 10/181,020 07/12/2002 PAT 6,890,617  
 which is a 371 of PCT/JP00/05553 08/18/2000

*ref 10/27/05*

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

JAPAN 005084/2000 01/13/2000  
 JAPAN 243398/2000 08/10/2000

*ref 10/27/05*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	JAPAN	DRAWING 6	CLAIMS 11	CLAIMS 2
Verified and Acknowledged	<i>Yuta Hotta</i> <i>ref 10/27/05</i> Examiner's Signature Initials				

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## TITLE

Porous adhesive sheet, semiconductor wafer with porous adhesive sheet and method of manufacture thereof

<input type="checkbox"/> All Fees
<input checked="" type="checkbox"/> 1.16 Fees ( Filing )